Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTIONS:**

1. **V IN (2 bond pads)**
2. **V OUT (2 bond pads)**
3. **V OUT SENSE**
4. **ADJUST**

**.090”**

**.082”**

**ANODE**

**TOP**

**BACK**

**Top Material: AgAs**

**Backside Material: AgGs**

**Bond Pad Size: See Above**

**Backside Potential: CATHODE**

**APPROVED BY: DK DIE SIZE .090 X .078” DATE: 11/10/21**

**MFG: MSC / UNITRODE THICKNESS .010” P/N: 1N5553**

**DG 10.1.2**

#### Rev B, 7/1